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To the Hon. Commissioner of Patents & Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Hidemitsu AOKI and Shinya YAMASAKI

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other

Execution Dates: March 14, 2000

2. Name and address of receiving party(ies):

Name:  
NEC CORPORATION

Street Address:  
7-1, Shiba 5-chome  
Minato-ku  
Tokyo, Japan

JC542 U.S. PTO  
09/534296  
03/23/00

4. Application number(s) or patent (numbers):

If this document is being filed together with a new application, the execution dates of the applications are: March 14, 2000

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

YOUNG & THOMPSON  
Second Floor  
745 South 23rd Street  
Arlington, VA 22202

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41).....\$ 40

- Enclosed
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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

03/31/2000 09534296

Mary Shelton  
Name of Person Signing

*Mary Shelton*  
Signature

March 23, 2000  
Date

Total number of pages including cover sheet: **[2]**

ASSIGNMENT

WHEREAS, HIDEMITSU AOKI and SHINYA YAMASAKI
c/o NEC Corporation, 7-1, Shiba 5-chome, Minatoku, Tokyo, Japan and
SHINYA YAMASAKI c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
Tokyo, Japan
have invented certain new and useful improvements in METHOD
AND APPARATUS FOR STORING A SEMICONDUCTOR WAFER AFTER ITS CMP POLISHING
for which we are about to make application for Letters
(I/we have made--or am/are about to make)

Patent of the United States of America;

AND WHEREAS, NEC Corporation, 7-1, Shiba 5-chome,
Minato-ku, Tokyo, Japan is
desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor from the
United States;

NOW THEREFORE, be it known by all whom it may concern, that for and in consideration of
One Dollars (\$ 1.00)
to us in hand paid, the receipt of which is hereby acknowledged the said ASSIGNOR
have assigned, sold, and set over, and by these presents do hereby assign, sell, and set over unto the said
ASSIGNEE, NEC Corporation
\* the full and exclusive right, title, and interest in and to the said invention,
as fully set forth and described in the:

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inapplicable
wording

(a) specification prepared and executed by us on the 14th day of March, 2000,
(b) application filed on the day of , 19, Serial No.
preparatory to obtaining Letters Patent therefor; said invention, application and Letters Patent to be
held and enjoyed by the said ASSIGNEE, NEC Corporation
for their own use and behoof, and for their legal representatives, to the full end of the term
for which said Letters Patent are granted, as fully and entirely as the same would have been held by
us had this assignment and sale not been made.

IN TESTIMONY WHEREOF, we hereunto set our hand and affix our seal at
this 14th day of March, A.D. 2000

Hidemitsu Aoki (Inventor's full Signature)

Shinya Yamasaki

Witness:

Nitoshi Ukwai

[Signature]